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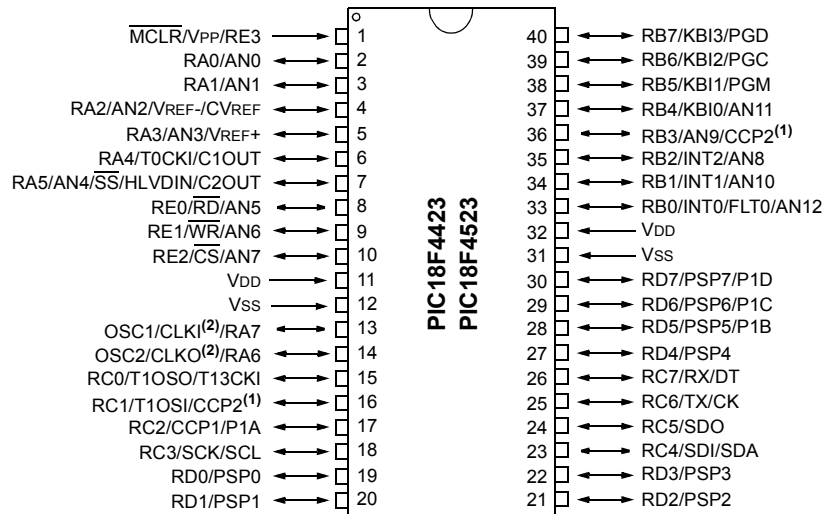
Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	I ² C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	25
Program Memory Size	16KB (8K x 16)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	768 x 8
Voltage - Supply (Vcc/Vdd)	4.2V ~ 5.5V
Data Converters	A/D 10x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	28-DIP (0.300", 7.62mm)
Supplier Device Package	28-SPDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18f2423-i-sp

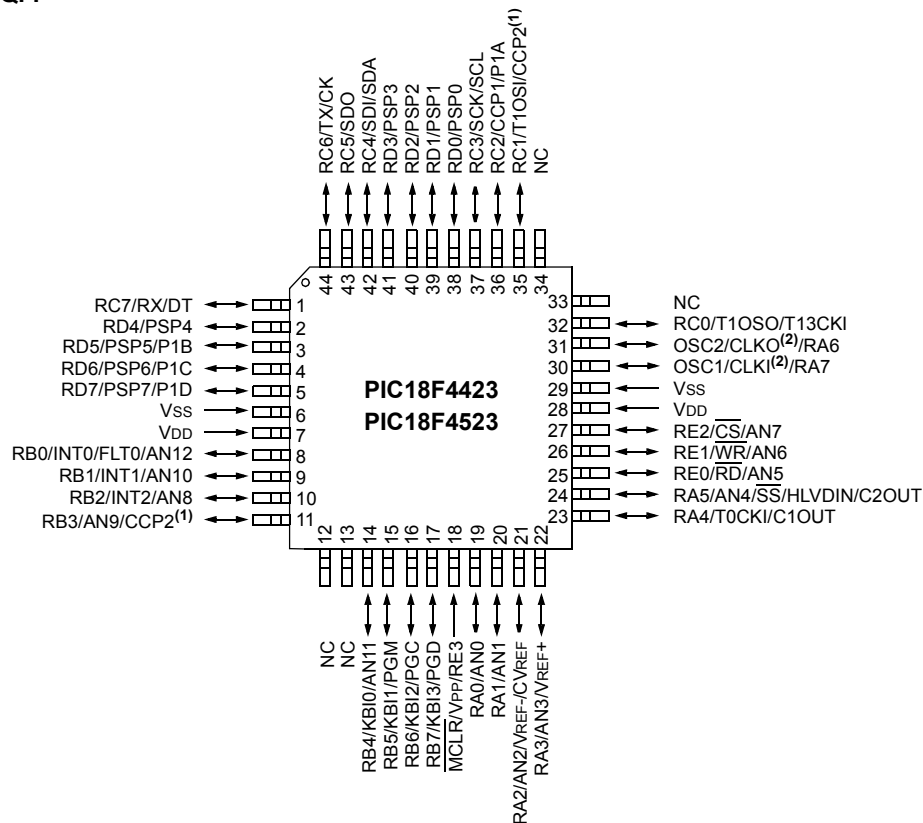
PIC18F2423/2523/4423/4523

Pin Diagrams (Continued)

40-Pin PDIP



44-Pin TQFP



Note 1: RB3 is the alternate pin for CCP2 multiplexing.

Note 2: OSC1/CLKI and OSC2/CLKO are only available in select oscillator modes and when these pins are not being used as digital I/O. For additional information, see **Section 2.0 "Oscillator Configurations"** of the "PIC18F2420/2520/4420/4520 Data Sheet" (DS39631).

PIC18F2423/2523/4423/4523

TABLE 1-3: PIC18F4423/4523 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number			Pin Type	Buffer Type	Description
	PDIP	QFN	TQFP			
RA0/AN0	2	19	19	I/O	TTL	PORTA is a bidirectional I/O port.
RA0				I	Analog	Digital I/O.
AN0						Analog Input 0.
RA1/AN1	3	20	20	I/O	TTL	Digital I/O.
RA1				I	Analog	Analog Input 1.
AN1						
RA2/AN2/VREF-/CVREF	4	21	21	I/O	TTL	Digital I/O.
RA2				I	Analog	Analog Input 2.
AN2				I	Analog	A/D reference voltage (low) input.
VREF-				O	Analog	Comparator reference voltage output.
CVREF						
RA3/AN3/VREF+	5	22	22	I/O	TTL	Digital I/O.
RA3				I	Analog	Analog Input 3.
AN3				I	Analog	A/D reference voltage (high) input.
VREF+						
RA4/T0CKI/C1OUT	6	23	23	I/O	ST	Digital I/O.
RA4				I	ST	Timer0 external clock input.
T0CKI				O	—	Comparator 1 output.
C1OUT						
RA5/AN4/SS/HLVDIN/C2OUT	7	24	24	I/O	TTL	Digital I/O.
RA5				I	Analog	Analog Input 4.
AN4				I	TTL	SPI slave select input.
SS				I	Analog	High/Low-Voltage Detect input.
HLVDIN				O	—	Comparator 2 output.
C2OUT						
RA6						See the OSC2/CLKO/RA6 pin.
RA7						See the OSC1/CLKI/RA7 pin.

Legend: TTL = TTL compatible input CMOS = CMOS compatible input or output
ST = Schmitt Trigger input with CMOS levels I = Input
O = Output P = Power
I²C = I²C™/SMBus

Note 1: Default assignment for CCP2 when Configuration bit, CCP2MX, is set.

2: Alternate assignment for CCP2 when Configuration bit, CCP2MX, is cleared.

PIC18F2423/2523/4423/4523

TABLE 1-3: PIC18F4423/4523 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number			Pin Type	Buffer Type	Description
	PDIP	QFN	TQFP			
RC0/T1OSO/T13CKI RC0 T1OSO T13CKI	15	34	32	I/O O I	ST — ST	PORTC is a bidirectional I/O port. Digital I/O. Timer1 oscillator output. Timer1/Timer3 external clock input.
RC1/T1OSI/CCP2 RC1 T1OSI CCP2 ⁽²⁾	16	35	35	I/O I I/O	ST CMOS ST	Digital I/O. Timer1 oscillator input. Capture 2 input/Compare 2 output/PWM2 output.
RC2/CCP1/P1A RC2 CCP1 P1A	17	36	36	I/O I/O O	ST ST —	Digital I/O. Capture 1 input/Compare 1 output/PWM1 output. Enhanced CCP1 output.
RC3/SCK/SCL RC3 SCK SCL	18	37	37	I/O I/O I/O	ST ST I ² C	Digital I/O. Synchronous serial clock input/output for SPI mode. Synchronous serial clock input/output for I ² C™ mode.
RC4/SDI/SDA RC4 SDI SDA	23	42	42	I/O I I/O	ST ST I ² C	Digital I/O. SPI data in. I ² C data I/O.
RC5/SDO RC5 SDO	24	43	43	I/O O	ST —	Digital I/O. SPI data out.
RC6/TX/CK RC6 TX CK	25	44	44	I/O O I/O	ST — ST	Digital I/O. EUSART asynchronous transmit. EUSART synchronous clock (see related RX/DT).
RC7/RX/DT RC7 RX DT	26	1	1	I/O I I/O	ST ST ST	Digital I/O. EUSART asynchronous receive. EUSART synchronous data (see related TX/CK).

Legend: TTL = TTL compatible input
ST = Schmitt Trigger input with CMOS levels
O = Output
I²C = I²C™/SMBus
CMOS = CMOS compatible input or output
I = Input
P = Power

Note 1: Default assignment for CCP2 when Configuration bit, CCP2MX, is set.

2: Alternate assignment for CCP2 when Configuration bit, CCP2MX, is cleared.

PIC18F2423/2523/4423/4523

TABLE 1-3: PIC18F4423/4523 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number			Pin Type	Buffer Type	Description
	PDIP	QFN	TQFP			
						PORTD is a bidirectional I/O port or a Parallel Slave Port (PSP) for interfacing to a microprocessor port. These pins have TTL input buffers when the PSP module is enabled.
RD0/PSP0	19	38	38	I/O	ST	Digital I/O.
RD0				I/O	TTL	Parallel Slave Port data.
PSP0						
RD1/PSP1	20	39	39	I/O	ST	Digital I/O.
RD1				I/O	TTL	Parallel Slave Port data.
PSP1						
RD2/PSP2	21	40	40	I/O	ST	Digital I/O.
RD2				I/O	TTL	Parallel Slave Port data.
PSP2						
RD3/PSP3	22	41	41	I/O	ST	Digital I/O.
RD3				I/O	TTL	Parallel Slave Port data.
PSP3						
RD4/PSP4	27	2	2	I/O	ST	Digital I/O.
RD4				I/O	TTL	Parallel Slave Port data.
PSP4						
RD5/PSP5/P1B	28	3	3	I/O	ST	Digital I/O.
RD5				I/O	TTL	Parallel Slave Port data.
PSP5				O	—	Enhanced CCP1 output.
P1B						
RD6/PSP6/P1C	29	4	4	I/O	ST	Digital I/O.
RD6				I/O	TTL	Parallel Slave Port data.
PSP6				O	—	Enhanced CCP1 output.
P1C						
RD7/PSP7/P1D	30	5	5	I/O	ST	Digital I/O.
RD7				I/O	TTL	Parallel Slave Port data.
PSP7				O	—	Enhanced CCP1 output.
P1D						

Legend: TTL = TTL compatible input CMOS = CMOS compatible input or output
ST = Schmitt Trigger input with CMOS levels I = Input
O = Output P = Power
I²C = I²C™/SMBus

Note 1: Default assignment for CCP2 when Configuration bit, CCP2MX, is set.
2: Alternate assignment for CCP2 when Configuration bit, CCP2MX, is cleared.

PIC18F2423/2523/4423/4523

TABLE 1-3: PIC18F4423/4523 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number			Pin Type	Buffer Type	Description
	PDIP	QFN	TQFP			
RE0/ $\overline{\text{RD}}$ /AN5 RE0 $\overline{\text{RD}}$ AN5	8	25	25	I/O I I	ST TTL Analog	<p>PORTE is a bidirectional I/O port.</p> <p>Digital I/O. Read control for Parallel Slave Port (see also $\overline{\text{WR}}$ and $\overline{\text{CS}}$ pins). Analog Input 5.</p>
RE1/ $\overline{\text{WR}}$ /AN6 RE1 $\overline{\text{WR}}$ AN6	9	26	26	I/O I I	ST TTL Analog	<p>Digital I/O. Write control for Parallel Slave Port (see $\overline{\text{CS}}$ and $\overline{\text{RD}}$ pins). Analog Input 6.</p>
RE2/ $\overline{\text{CS}}$ /AN7 RE2 $\overline{\text{CS}}$ AN7	10	27	27	I/O I I	ST TTL Analog	<p>Digital I/O. Chip select control for Parallel Slave Port (see related $\overline{\text{RD}}$ and $\overline{\text{WR}}$). Analog Input 7.</p>
RE3	—	—	—	—	—	See $\overline{\text{MCLR}}/\text{VPP}/\text{RE3}$ pin.
Vss	12, 31	6, 30, 31	6, 29	P	—	Ground reference for logic and I/O pins.
VDD	11, 32	7, 8, 28, 29	7, 28	P	—	Positive supply for logic and I/O pins.
NC	—	13	12, 13, 33, 34	—	—	No connect.

Legend: TTL = TTL compatible input CMOS = CMOS compatible input or output
ST = Schmitt Trigger input with CMOS levels I = Input
O = Output P = Power
I²C = I²C™/SMBus

Note 1: Default assignment for CCP2 when Configuration bit, CCP2MX, is set.

2: Alternate assignment for CCP2 when Configuration bit, CCP2MX, is cleared.

PIC18F2423/2523/4423/4523

NOTES:

PIC18F2423/2523/4423/4523

The value in the ADRESH:ADRESL registers is unknown following POR and BOR Resets and is not affected by any other Reset.

After the A/D module has been configured as desired, the selected channel must be acquired before the conversion is started. The analog input channels must have their corresponding TRIS bits selected as inputs. To determine acquisition time, see **Section 2.1 “A/D Acquisition Requirements”**.

After this acquisition time has elapsed, the A/D conversion can be started. An acquisition time can be programmed to occur between setting the GO/DONE bit and the actual start of the conversion.

The following steps should be followed to perform an A/D conversion:

1. Configure the A/D module:
 - Configure analog pins, voltage reference and digital I/O (ADCON1)
 - Select A/D input channel (ADCON0)
 - Select A/D acquisition time (ADCON2)
 - Select A/D conversion clock (ADCON2)
 - Turn on the A/D module (ADCON0)
2. Configure the A/D interrupt (if desired):
 - Clear ADIF bit
 - Set ADIE bit
 - Set GIE bit
3. Wait the required acquisition time (if required).
4. Start conversion by setting the GO/DONE bit (ADCON0<1>).

5. Wait for the A/D conversion to complete by either:
 - Polling for the GO/DONE bit to be cleared
 OR
 - Waiting for the A/D interrupt
6. Read the A/D Result registers (ADRESH:ADRESL) and clear the ADIF bit, if required.
7. For the next conversion, go to step 1 or step 2, as required.

The A/D conversion time per bit is defined as TAD. A minimum wait of 2 TAD is required before the next acquisition starts.

FIGURE 2-2: A/D TRANSFER FUNCTION

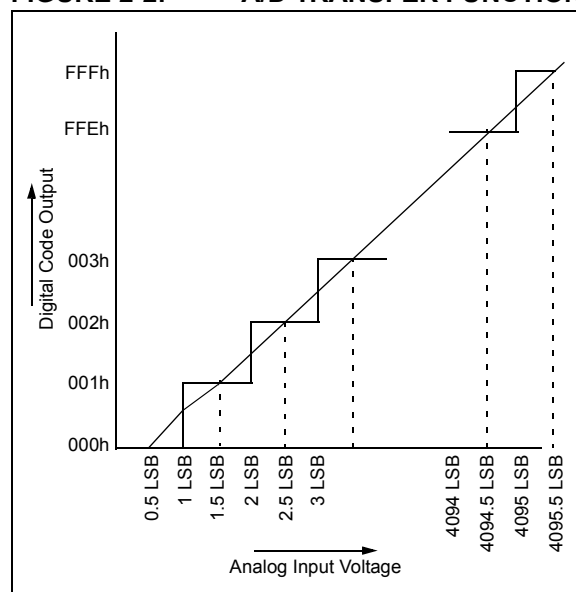
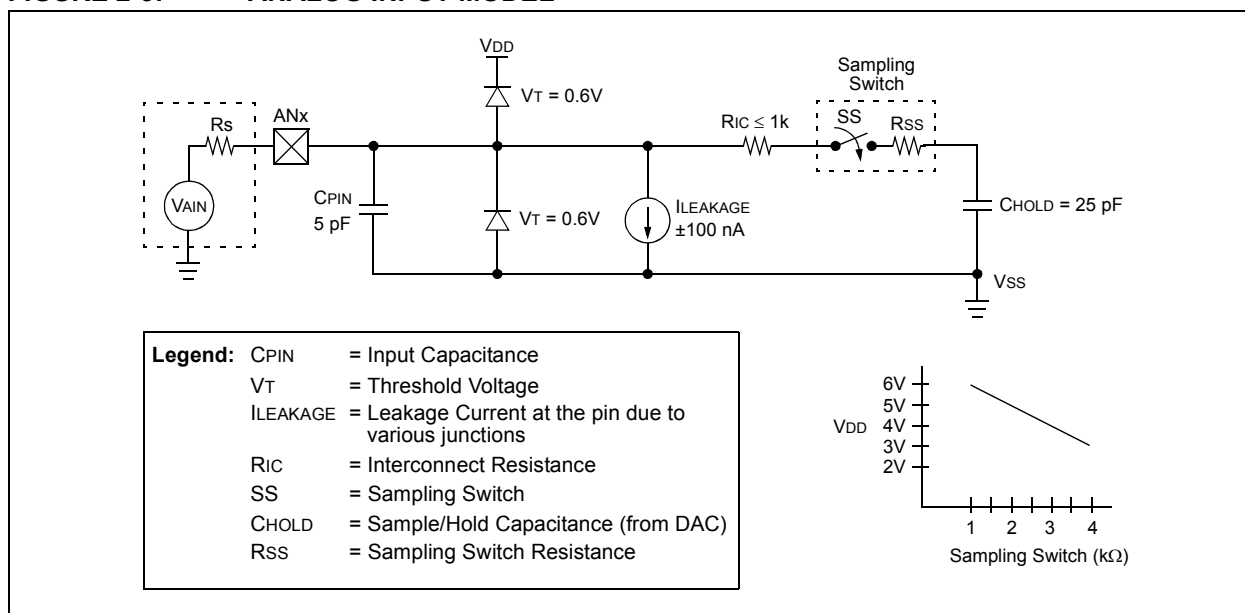


FIGURE 2-3: ANALOG INPUT MODEL



PIC18F2423/2523/4423/4523

2.1 A/D Acquisition Requirements

For the A/D Converter to meet its specified accuracy, the charge holding capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The analog input model is shown in Figure 2-3.

The source impedance (Rs) and the internal sampling switch (Rss) impedance directly affect the time required to charge the capacitor, CHOLD. The sampling switch (Rss) impedance varies over the device voltage (VDD). The source impedance affects the offset voltage at the analog input (due to pin leakage current). **The maximum recommended impedance for analog sources is 2.5 kΩ.**

After the analog input channel is selected (changed), the channel must be sampled for at least the minimum acquisition time before starting a conversion.

Note: When the conversion is started, the holding capacitor is disconnected from the input pin.

To calculate the minimum acquisition time, Equation 2-1 may be used. This equation assumes that 1/2 LSb error is used (4,096 steps for the A/D). The 1/2 LSb error is the maximum error allowed for the A/D to meet its specified resolution.

Example 2-3 shows the calculation of the minimum required acquisition time, TACQ. This calculation is based on the application system assumptions shown in Table 2-1:

TABLE 2-1: TAcQ ASSUMPTIONS

CHOLD	=	25 pF
Rs	=	2.5 kΩ
Conversion Error	≤	1/2 LSb
VDD	=	3V → Rss = 4 kΩ
Temperature	=	85°C (system maximum)

EQUATION 2-1: ACQUISITION TIME

$$\begin{aligned} \text{TACQ} &= \text{Amplifier Settling Time} + \text{Holding Capacitor Charging Time} + \text{Temperature Coefficient} \\ &= \text{TAMP} + \text{TC} + \text{TCOFF} \end{aligned}$$

EQUATION 2-2: A/D MINIMUM CHARGING TIME

$$\begin{aligned} \text{VHOLD} &= (\text{VREF} - (\text{VREF}/4096)) \cdot (1 - e^{-(\text{TC}/\text{CHOLD}(\text{RIC} + \text{RSS} + \text{RS})))} \\ \text{or} \\ \text{TC} &= -(\text{CHOLD})(\text{RIC} + \text{RSS} + \text{RS}) \ln(1/4096) \end{aligned}$$

EQUATION 2-3: CALCULATING THE MINIMUM REQUIRED ACQUISITION TIME

$$\begin{aligned} \text{TACQ} &= \text{TAMP} + \text{TC} + \text{TCOFF} \\ \text{TAMP} &= 0.2 \mu\text{s} \\ \text{TCOFF} &= (\text{Temp} - 25^\circ\text{C})(0.02 \mu\text{s}/^\circ\text{C}) \\ &\quad (85^\circ\text{C} - 25^\circ\text{C})(0.02 \mu\text{s}/^\circ\text{C}) \\ &\quad 1.2 \mu\text{s} \end{aligned}$$

Temperature coefficient is only required for temperatures > 25°C. Below 25°C, TCOFF = 0 ms.

$$\begin{aligned} \text{TC} &= -(\text{CHOLD})(\text{RIC} + \text{RSS} + \text{RS}) \ln(1/4096) \mu\text{s} \\ &\quad -(25 \text{ pF})(1 \text{ k}\Omega + 4 \text{ k}\Omega + 2.5 \text{ k}\Omega) \ln(0.0004883) \mu\text{s} \\ &\quad 1.56 \mu\text{s} \\ \text{TACQ} &= 0.2 \mu\text{s} + 1.56 \mu\text{s} + 1.2 \mu\text{s} \\ &\quad 2.96 \mu\text{s} \end{aligned}$$

2.4 Operation in Power-Managed Modes

The selection of the automatic acquisition time and A/D conversion clock is determined in part by the clock source and frequency while in a power-managed mode.

If the A/D is expected to operate while the device is in a power-managed mode, the $ADCS<2:0>$ bits in $ADCON2$ should be updated in accordance with the clock source to be used. The $ACQT<2:0>$ bits do not need to be adjusted as the $ADCS<2:0>$ bits adjust the TAD time for the new clock speed. After entering the mode, an A/D acquisition or conversion may be started. Once started, the device should continue to be clocked by the same clock source until the conversion has been completed.

If desired, the device may be placed into the corresponding Idle mode during the conversion. If the device clock frequency is less than 1 MHz, the A/D RC clock source should be selected.

Operation in Sleep mode requires the A/D FRC clock to be selected. If bits, $ACQT<2:0>$, are set to '000' and a conversion is started, the conversion will be delayed one instruction cycle to allow execution of the `SLEEP` instruction and entry to Sleep mode. The $IDLEN$ bit ($OSCCON<7>$) must have already been cleared prior to starting the conversion.

2.5 Configuring Analog Port Pins

The $ADCON1$, $TRISA$, $TRISB$ and $TRISE$ registers all configure the A/D port pins. The port pins needed as analog inputs must have their corresponding $TRIS$ bits set (input). If the $TRIS$ bit is cleared (output), the digital output level (V_{OH} or V_{OL}) will be converted.

The A/D operation is independent of the state of the $CHS<3:0>$ bits and the $TRIS$ bits.

- Note 1:** When reading the $PORT$ register, all pins configured as analog input channels will read as cleared (a low level). Analog conversion on pins configured as digital pins can be performed. The voltage on the pin will be accurately converted.

2: Analog levels on any pin defined as a digital input may cause the digital input buffer to consume current out of the device's specification limits.

3: The $PBADEN$ bit in Configuration Register 3H configures $PORTB$ pins to reset as analog or digital pins by controlling how the $PCFG<3:0>$ bits in $ADCON1$ are reset.

2.6 A/D Conversions

Figure 2-4 shows the operation of the A/D Converter after the $\overline{\text{GO/DONE}}$ bit has been set and the $\text{ACQT}<2:0>$ bits are cleared. A conversion is started after the following instruction to allow entry into Sleep mode before the conversion begins.

Figure 2-5 shows the operation of the A/D Converter after the $\overline{\text{GO/DONE}}$ bit has been set, the $\text{ACQT}<2:0>$ bits have been set to '010' and a 4 TAD acquisition time has been selected before the conversion starts.

Clearing the $\overline{\text{GO/DONE}}$ bit during a conversion will abort the current conversion. The A/D Result register pair will NOT be updated with the partially completed A/D conversion sample. This means, the ADRESH:ADRESL registers will continue to contain the value of the last completed conversion (or the last value written to the ADRESH:ADRESL registers).

After the A/D conversion is completed or aborted, a 2 Tcy wait is required before the next acquisition can be started. After this wait, acquisition on the selected channel is automatically started.

Note: The $\overline{\text{GO/DONE}}$ bit should **NOT** be set in the same instruction that turns on the A/D. Code should wait at least 3 TAD after enabling the A/D before beginning an acquisition and conversion cycle.

2.7 Discharge

The discharge phase is used to initialize the value of the holding capacitor. The array is discharged before every sample. This feature helps to optimize the unity-gain amplifier, as the circuit always needs to charge the capacitor array, rather than charge/discharge based on previous measure values.

FIGURE 2-4: A/D CONVERSION TAD CYCLES ($\text{ACQT}<2:0> = 000$, $\text{Tacq} = 0$)

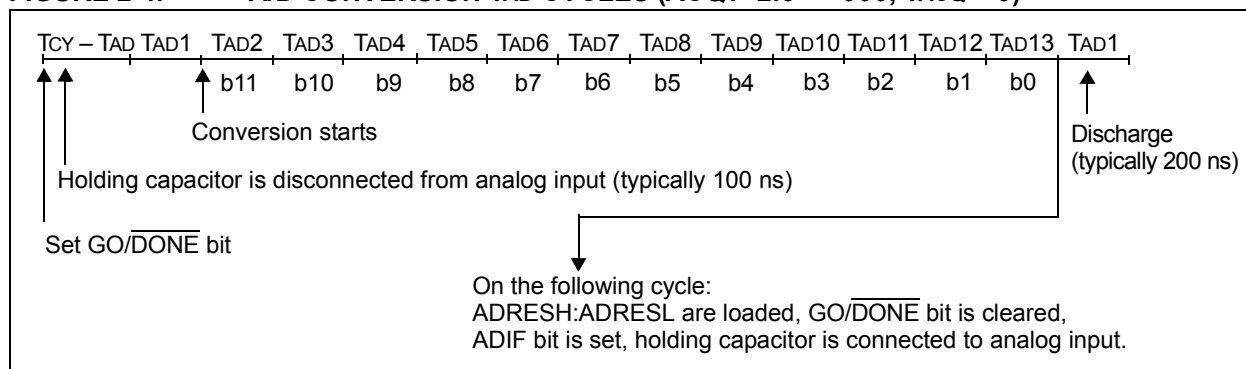
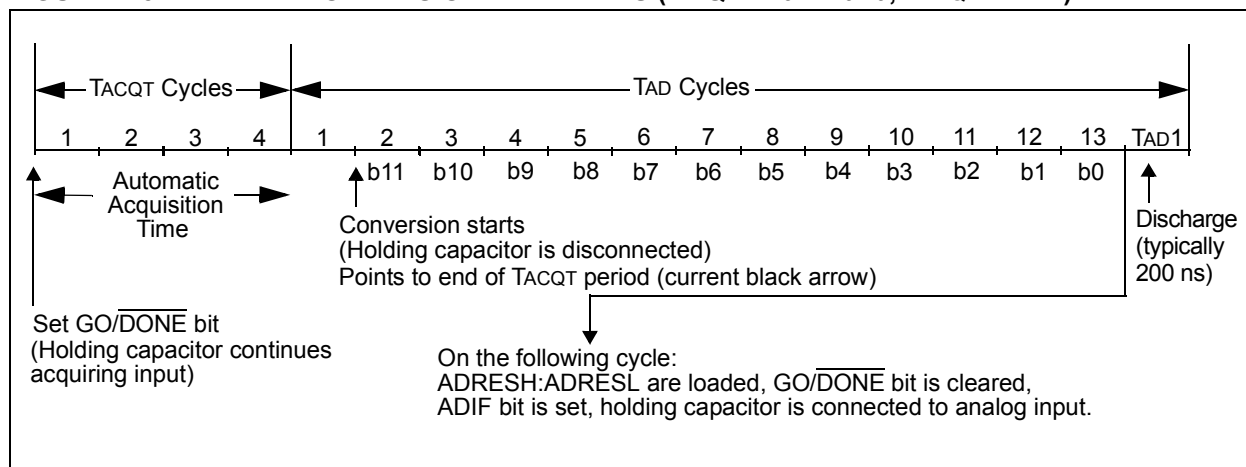


FIGURE 2-5: A/D CONVERSION TAD CYCLES ($\text{ACQT}<2:0> = 010$, $\text{Tacq} = 4 \text{ TAD}$)



PIC18F2423/2523/4423/4523

3.0 SPECIAL FEATURES OF THE CPU

Note: For additional details on the Configuration bits, refer to **Section 23.1 “Configuration Bits”** in the “PIC18F2420/2520/4420/4520 Data Sheet” (DS39631). Device ID information presented in this section is for the PIC18F2423/2523/4423/4523 devices only.

3.1 Device ID Registers

The Device ID registers are read-only registers. They identify the device type and revision for device programmers and can be read by firmware using table reads.

TABLE 3-1: DEVICE IDs

File Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Default/ Unprogrammed Value
3FFFFEh	DEV3	DEV2	DEV1	DEV0	REV3	REV2	REV1	REV0	xxxx xxxx ⁽²⁾
3FFFFh	DEV11	DEV10	DEV9	DEV8	DEV7	DEV6	DEV5	DEV4	xxxx xxxx ⁽²⁾

Legend: x = unknown, u = unchanged, — = unimplemented. Shaded cells are unimplemented, read as '0'.

Note 1: DEVID registers are read-only and cannot be programmed by the user.

2: See Register 3-1 and Register 3-2 for DEVID1 and DEVID2 values.

REGISTER 3-1: DEVID1: DEVICE ID REGISTER 1 FOR PIC18F2423/2523/4423/4523

R	R	R	R	R	R	R	R
DEV3	DEV2	DEV1	DEV0	REV3	REV2	REV1	REV0
bit 7				bit 0			

Legend:

R = Read-only bit

P = Programmable bit

U = Unimplemented bit, read as '0'

-n = Value when device is unprogrammed

u = Unchanged from programmed state

bit 7-4 **DEV<3:0>:** Device ID bits

1101 = PIC18F4423

1001 = PIC18F4523

0101 = PIC18F2423

0001 = PIC18F2523

bit 3-0 **REV<3:0>:** Revision ID bits

These bits are used to indicate the device revision.

PIC18F2423/2523/4423/4523

REGISTER 3-2: DEVID2: DEVICE ID REGISTER 2 FOR PIC18F2423/2523/4423/4523

R	R	R	R	R	R	R	R
DEV11 ⁽¹⁾	DEV10 ⁽¹⁾	DEV9 ⁽¹⁾	DEV8 ⁽¹⁾	DEV7 ⁽¹⁾	DEV6 ⁽¹⁾	DEV5 ⁽¹⁾	DEV4 ⁽¹⁾
bit 7							bit 0

Legend:

R = Read-only bit

P = Programmable bit

U = Unimplemented bit, read as '0'

-n = Value when device is unprogrammed

u = Unchanged from programmed state

bit 7-0 **DEV<11:4>**: Device ID bits⁽¹⁾

These bits are used with the DEV<3:0> bits in Device ID Register 1 to identify the part number.

0001 0001 = PIC18F2423/2523 devices

0001 0000 = PIC18F4423/4523 devices

Note 1: These values for DEV<11:4> may be shared with other devices. The specific device is always identified by using the entire DEV<11:0> bit sequence.

PIC18F2423/2523/4423/4523

4.0 ELECTRICAL CHARACTERISTICS

Note: Other than some basic data, this section documents only the PIC18F2423/2523/4423/4523 devices' specifications that differ from those of the PIC18F2420/2520/4420/4520 devices. For detailed information on the electrical specifications shared by the PIC18F2423/2523/4423/4523 and PIC18F2420/2520/4420/4520 devices, see the "PIC18F2420/2520/4420/4520 Data Sheet" (DS39631).

Absolute Maximum Ratings^(†)

Ambient temperature under bias	-40°C to +125°C
Storage temperature	-65°C to +150°C
Voltage on any pin with respect to V _{SS} (except V _{DD} and $\overline{\text{MCLR}}$)	-0.3V to (V _{DD} + 0.3V)
Voltage on V _{DD} with respect to V _{SS}	-0.3V to +7.5V
Voltage on $\overline{\text{MCLR}}$ with respect to V _{SS} (Note 2)	0V to +13.25V
Total power dissipation (Note 1)	1.0W
Maximum current out of V _{SS} pin	300 mA
Maximum current into V _{DD} pin	250 mA
Input clamp current, I _{IK} (V _I < 0 or V _I > V _{DD})	±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{DD})	±20 mA
Maximum output current sunk by any I/O pin	25 mA
Maximum output current sourced by any I/O pin	25 mA
Maximum current sunk by all ports	200 mA
Maximum current sourced by all ports	200 mA

Note 1: Power dissipation is calculated as follows:

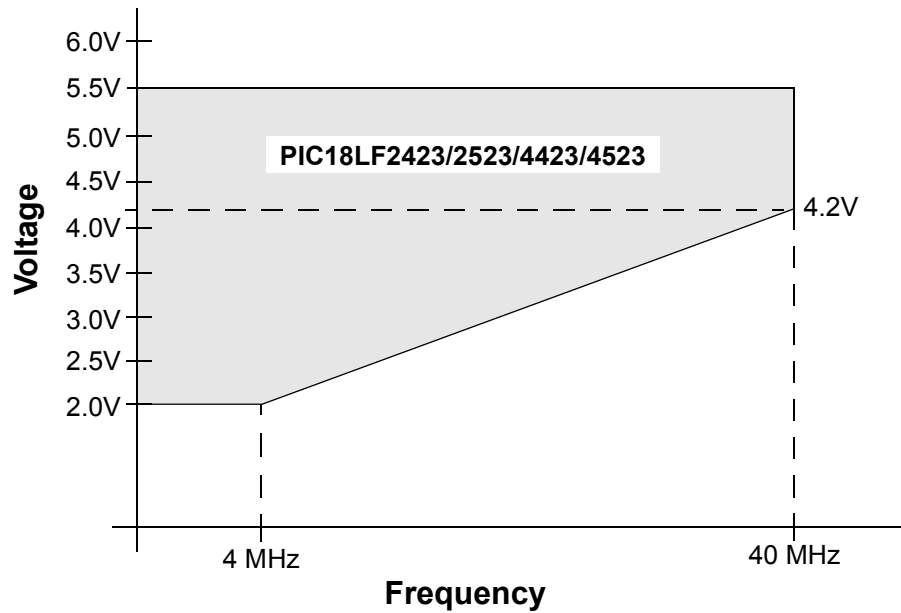
$$P_{dis} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum (V_{OL} \times I_{OL})$$

- 2:** Voltage spikes below V_{SS} at the $\overline{\text{MCLR}}$ /V_{PP}/RE3 pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a "low" level to the $\overline{\text{MCLR}}$ /V_{PP}/RE3 pin, rather than pulling this pin directly to V_{SS}.

† NOTICE: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

PIC18F2423/2523/4423/4523

FIGURE 4-3: PIC18LF2423/2523/4423/4523 VOLTAGE-FREQUENCY GRAPH (INDUSTRIAL)



$$F_{MAX} = (16.36 \text{ MHz/V}) (V_{DDAPP\text{MIN}} - 2.0\text{V}) + 4 \text{ MHz}$$

Note: $V_{DDAPP\text{MIN}}$ is the minimum voltage of the PIC[®] device in the application.

PIC18F2423/2523/4423/4523

**TABLE 4-1: A/D CONVERTER CHARACTERISTICS: PIC18F2423/2523/4423/4523 (INDUSTRIAL)
PIC18LF2423/2523/4423/4523 (INDUSTRIAL)**

Param No.	Sym	Characteristic	Min	Typ	Max	Units	Conditions	
A01	NR	Resolution	—	—	12	bit		$\Delta V_{REF} \geq 3.0V$
A03	EIL	Integral Linearity Error	—	$<\pm 1$	± 2.0	LSB	$V_{DD} = 3.0V$	$\Delta V_{REF} \geq 3.0V$
			—	—	± 2.0	LSB	$V_{DD} = 5.0V$	
A04	EDL	Differential Linearity Error	—	$<\pm 1$	$+1.5/-1.0$	LSB	$V_{DD} = 3.0V$	$\Delta V_{REF} \geq 3.0V$
			—	—	$+1.5/-1.0$	LSB	$V_{DD} = 5.0V$	
A06	EOFF	Offset Error	—	$<\pm 1$	± 5	LSB	$V_{DD} = 3.0V$	$\Delta V_{REF} \geq 3.0V$
			—	—	± 3	LSB	$V_{DD} = 5.0V$	
A07	EGN	Gain Error	—	$<\pm 1$	± 1.25	LSB	$V_{DD} = 3.0V$	$\Delta V_{REF} \geq 3.0V$
			—	—	± 2.00	LSB	$V_{DD} = 5.0V$	
A10	—	Monotonicity	Guaranteed ⁽¹⁾			—		$V_{SS} \leq V_{AIN} \leq V_{REF}$
A20	ΔV_{REF}	Reference Voltage Range ($V_{REFH} - V_{REFL}$)	3	—	$V_{DD} - V_{SS}$	V		For 12-bit resolution.
A21	V_{REFH}	Reference Voltage High	$V_{SS} + 3.0V$	—	$V_{DD} + 0.3V$	V		For 12-bit resolution.
A22	V_{REFL}	Reference Voltage Low	$V_{SS} - 0.3V$	—	$V_{DD} - 3.0V$	V		For 12-bit resolution.
A25	V_{AIN}	Analog Input Voltage	V_{REFL}	—	V_{REFH}	V		
A30	Z_{AIN}	Recommended Impedance of Analog Voltage Source	—	—	2.5	k Ω		
A50	I_{REF}	V_{REF} Input Current ⁽²⁾	—	—	5	μA		During V_{AIN} acquisition. During A/D conversion cycle.
			—	—	150	μA		

- Note 1:** The A/D conversion result never decreases with an increase in the input voltage and has no missing codes.
- Note 2:** V_{REFH} current is from the RA3/AN3/ V_{REF+} pin or V_{DD} , whichever is selected as the V_{REFH} source. V_{REFL} current is from the RA2/AN2/ V_{REF-}/CV_{REF} pin or V_{SS} , whichever is selected as the V_{REFL} source.

5.0 PACKAGING INFORMATION

For packaging information, see **Section 28.0 “Packaging Information”** in the *“PIC18F2420/2520/4420/4520 Data Sheet”* (DS39631).

PIC18F2423/2523/4423/4523

APPENDIX A: REVISION HISTORY

Revision A (June 2006)

Original data sheet for PIC18F2423/2523/4423/4523 devices.

Revision B (January 2007)

This revision includes updates to the packaging diagrams.

Revision C (September 2009)

Electrical specifications updated. Preliminary condition status removed. Converted document to the "mini data sheet" format.

APPENDIX B: DEVICE DIFFERENCES

The differences between the devices listed in this data sheet are shown in Table B-1.

TABLE B-1: DEVICE DIFFERENCES

Features	PIC18F2423	PIC18F2523	PIC18F4423	PIC18F4523
Program Memory (Bytes)	16384	32768	16384	32768
Program Memory (Instructions)	8192	16384	8192	16384
Interrupt Sources	19	19	20	20
I/O Ports	Ports A, B, C, (E)	Ports A, B, C, (E)	Ports A, B, C, D, E	Ports A, B, C, D, E
Capture/Compare/PWM Modules	2	2	1	1
Enhanced Capture/Compare/PWM Modules	0	0	1	1
Parallel Communications (PSP)	No	No	Yes	Yes
12-Bit Analog-to-Digital Module	10 Input Channels	10 Input Channels	13 Input Channels	13 Input Channels
Packages	28-Pin PDIP 28-Pin SOIC 28-Pin QFN	28-Pin PDIP 28-Pin SOIC 28-Pin QFN	40-Pin PDIP 44-Pin TQFP 44-Pin QFN	40-Pin PDIP 44-Pin TQFP 44-Pin QFN

APPENDIX E: MIGRATION FROM MID-RANGE TO ENHANCED DEVICES

A detailed discussion of the differences between the mid-range MCU devices (i.e., PIC16CXXX) and the enhanced devices (i.e., PIC18FXXX) is provided in AN716, *"Migrating Designs from PIC16C74A/74B to PIC18C442"*. The changes discussed, while device specific, are generally applicable to all mid-range to enhanced device migrations.

This Application Note is available as Literature Number DS00716.

APPENDIX F: MIGRATION FROM HIGH-END TO ENHANCED DEVICES

A detailed discussion of the migration pathway and differences between the high-end MCU devices (i.e., PIC17CXXX) and the enhanced devices (i.e., PIC18FXXX) is provided in AN726, *"PIC17CXXX to PIC18CXXX Migration"*. This Application Note is available as Literature Number DS00726.

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